

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10073173	FILING DATE 02/13/2002	CLASS 438	SUBCLASS 5.2	GAU 2812	EXAMINER L f. A.M.
**APPLICANTS: Kim Gu-Sung;					
**CONTINUING DATA VERIFIED:					
**FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 259/014	
TITLE : Wafer level package with air pads and manufacturing method thereof					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED		
		Assistant Examiner	Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drawg.	Figs. Drawg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
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